

JEDEC STANDARD

External Visual

JESD22-B101D

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JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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METHOD B101D

EXTERNAL VISUAL

(From JEDEC Board Ballot JCB-21-46, formulated under the cognizance of the JC-14.1 Subcommittee on Reliability Test Methods for Packaged Devices)

1 Scope

External visual inspection is an examination of the external surfaces, construction, marking, and workmanship of a finished packaged device. External visual is a noninvasive and nondestructive test. It is functional for qualification, quality monitoring, and lot acceptance.

This test method is applicable to:

- finished packaged devices only (hereafter referred to as ‘devices’);

NOTE Devices sampled for external visual inspection must be considered physically representative of the as-shipped product.

- all solid-state device package types/styles;
- devices having attachments as shipped (see clause 3 for definition).

This test method **is not** applicable to:

- customer-processed devices (see clause 3 for definition);
- piece parts incoming to a device assembly operation, or to sub-assemblies in a manufacturing line (WIP);
- the carrier, dry bag, packing, or container used to ship devices;
- the orientation or loading aspects of devices in carriers, (applicable to the device only);
- the internal, non-viewable features of a device.

This test method does not apply to or require any inspection, measurement, or analysis other than the procedure described in clause 5.

This test method does not preclude the use of specialized tools or equipment to inspect or measure devices for conformance to physical specifications.